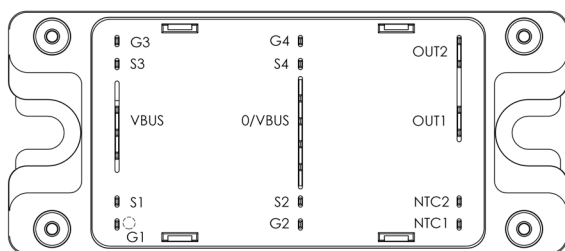
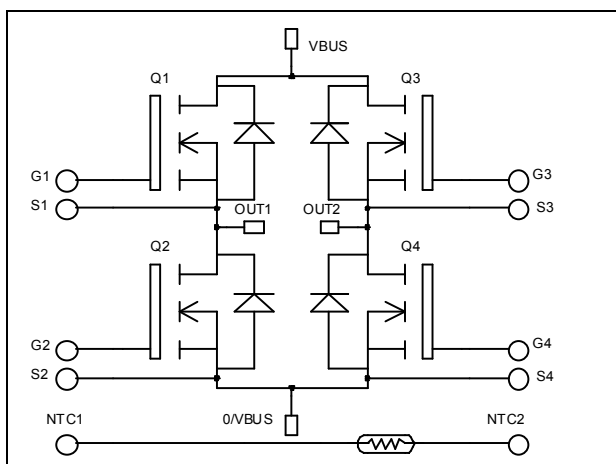


Full - Bridge MOSFET Power Module

$$V_{DSS} = 200V$$

$$R_{DSon} = 16m\Omega \text{ typ @ } T_j = 25^\circ C$$

$$I_D = 104A \text{ @ } T_c = 25^\circ C$$



Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

Features

- Power MOS 7[®] FREDFETs
 - Low R_{DSon}
 - Low input and Miller capacitance
 - Low gate charge
 - Fast intrinsic reverse diode
 - Avalanche energy rated
 - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
 - Symmetrical design
 - Lead frames for power connections
- Internal thermistor for temperature monitoring
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- RoHS Compliant

Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_{DSS}	Drain - Source Breakdown Voltage	200	V
I_D	Continuous Drain Current	$T_c = 25^\circ C$	A
		$T_c = 80^\circ C$	
I_{DM}	Pulsed Drain current	416	
V_{GS}	Gate - Source Voltage	± 30	V
R_{DSon}	Drain - Source ON Resistance	19	m Ω
P_D	Maximum Power Dissipation	$T_c = 25^\circ C$	W
I_{AR}	Avalanche current (repetitive and non repetitive)	104	A
E_{AR}	Repetitive Avalanche Energy	50	mJ
E_{AS}	Single Pulse Avalanche Energy	3000	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 200V$ $T_j = 25^\circ\text{C}$			250	μA
		$V_{GS} = 0V, V_{DS} = 160V$ $T_j = 125^\circ\text{C}$			1000	
$R_{DS(on)}$	Drain – Source on Resistance	$V_{GS} = 10V, I_D = 52A$		16	19	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 2.5\text{mA}$	3		5	V
I_{GSS}	Gate – Source Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$			± 100	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1\text{MHz}$		7220		pF
C_{oss}	Output Capacitance			2330		
C_{rss}	Reverse Transfer Capacitance			146		
Q_g	Total gate Charge	$V_{GS} = 10V$ $V_{Bus} = 100V$ $I_D = 104A$		140		nC
Q_{gs}	Gate – Source Charge			53		
Q_{gd}	Gate – Drain Charge			67		
$T_{d(on)}$	Turn-on Delay Time	Inductive switching @ 125°C $V_{GS} = 15V$ $V_{Bus} = 133V$ $I_D = 104A$ $R_G = 5\Omega$		32		ns
T_r	Rise Time			64		
$T_{d(off)}$	Turn-off Delay Time			88		
T_f	Fall Time			116		
E_{on}	Turn-on Switching Energy	Inductive switching @ 25°C $V_{GS} = 15V, V_{Bus} = 133V$ $I_D = 104A, R_G = 5\Omega$		849		μJ
E_{off}	Turn-off Switching Energy			929		
E_{on}	Turn-on Switching Energy	Inductive switching @ 125°C $V_{GS} = 15V, V_{Bus} = 133V$ $I_D = 104A, R_G = 5\Omega$		936		μJ
E_{off}	Turn-off Switching Energy			986		

Source - Drain diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I _S	Continuous Source current (Body diode)		T _C = 25°C			104	A
			T _C = 80°C			77	
V _{SD}	Diode Forward Voltage	V _{GS} = 0V, I _S = - 104A				1.3	V
dv/dt	Peak Diode Recovery ❶					5	V/ns
t _{rr}	Reverse Recovery Time	I _S = - 104A V _R = 133V di _S /dt = 100A/μs	T _j = 25°C			230	ns
			T _j = 125°C			450	
Q _{rr}	Reverse Recovery Charge		T _j = 25°C		0.9		μC
			T _j = 125°C		3.4		

❶ dv/dt numbers reflect the limitations of the circuit rather than the device itself.

$I_S \leq -104A$ $di/dt \leq 700A/\mu\text{s}$ $V_R \leq V_{DSS}$ $T_j \leq 150^\circ\text{C}$



<i>Symbol</i>	<i>Characteristic</i>	<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
R _{thJC}	Junction to Case Thermal Resistance			0.32	°C/W
V _{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz	4000			V
T _J	Operating junction temperature range	-40		150	°C
T _{STG}	Storage Temperature Range	-40		125	
T _C	Operating Case Temperature	-40		100	
Torque	Mounting torque				
	To Heatsink				
	M5	2.5		4.7	N.m
Wt	Package Weight			160	g

<i>Symbol</i>	<i>Characteristic</i>	<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
R ₂₅	Resistance @ 25°C		50		kΩ
B _{25/85}	T ₂₅ = 298.15 K		3952		K

T: Thermistor temperature
 R_T : Thermistor value at T

Technical drawing of a mechanical part, showing three views: Top View, Front View, and Side View.

Top View Dimensions:

- Overall Width: 93 ± 0.50
- Overall Height: 80 ± 0.20
- Distance from Left Edge to Center of First Hole: 11.6^*
- Distance between Centers of First Two Holes: 30.50^*
- Distance between Centers of Last Two Holes: 26.40^*
- Distance from Right Edge to Center of Last Hole: 11.6^*
- Hole Diameters: $\varnothing 6.1 \pm 0.2$ and $\varnothing 2.50 \pm 0.10$
- Other Dimensions: 15.24^* , 11.43^* , 5.72^* , 3.81^* , 1.91^* , 0 , $5.50 - 0.05$, 11 ± 0.5

Front View Dimensions:

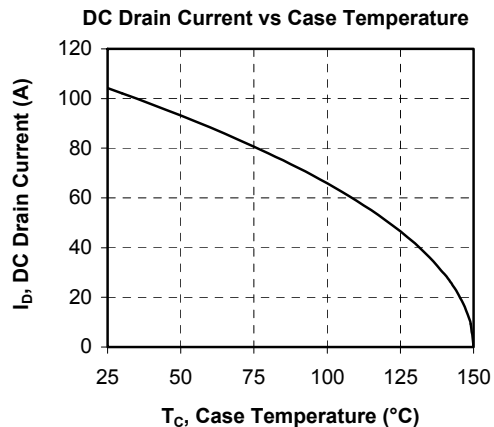
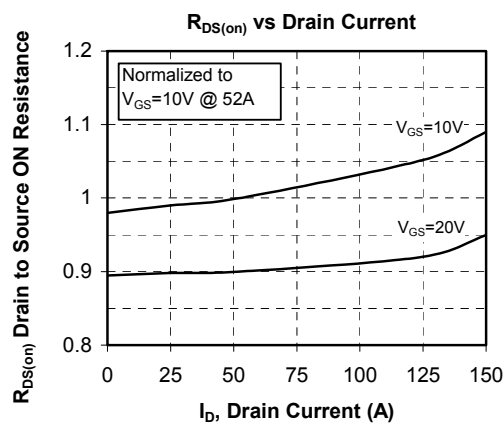
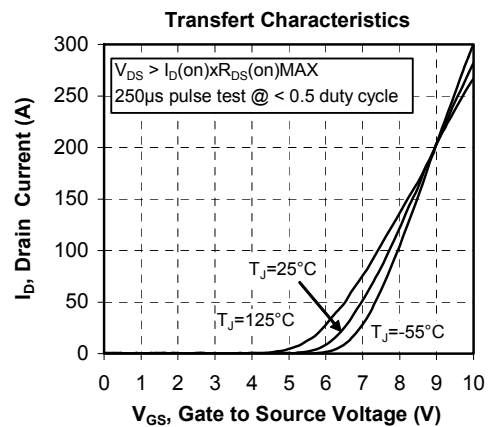
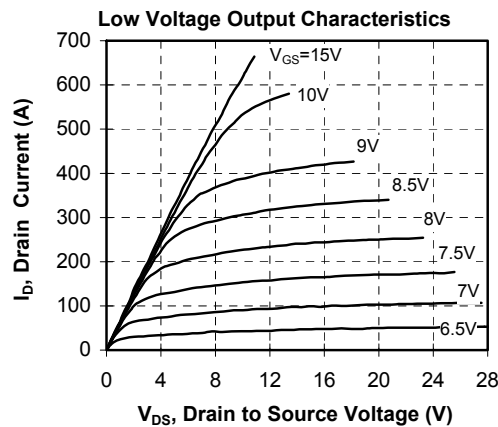
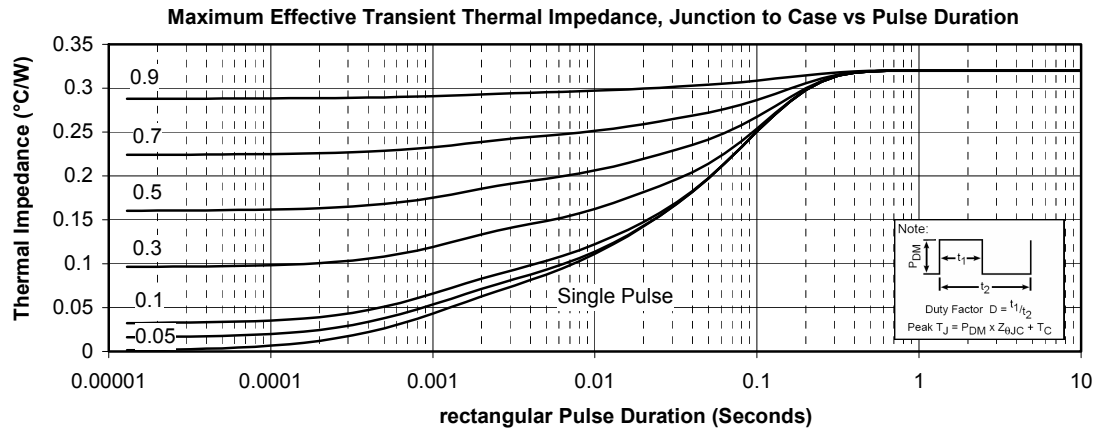
- Overall Width: 78.50 ± 0.25
- Overall Height: 17.20 ± 0.30
- Distance from Top Edge to Center of First Hole: 13 ± 0.50
- Distance from Top Edge to Center of Last Hole: 1 ± 0.10
- Distance from Top Edge to Center of Last Hole: 7 ± 0.20
- Hole Diameter: $\varnothing 2 \pm 0.10$

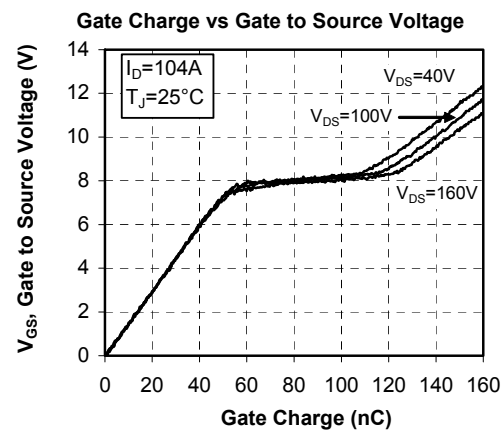
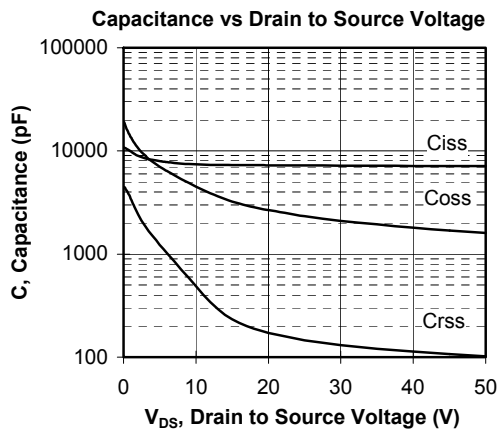
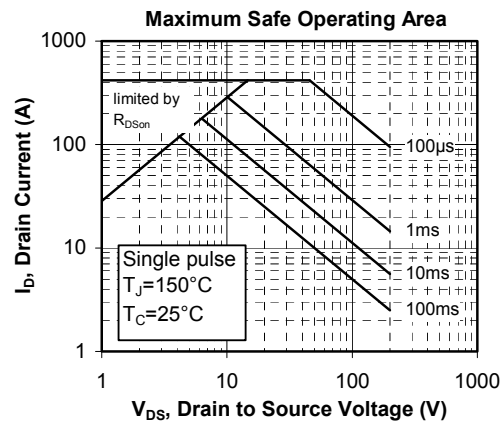
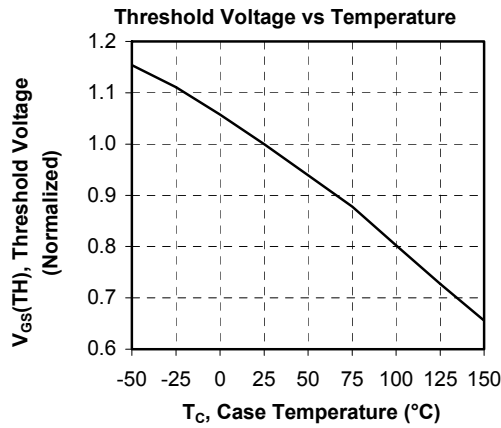
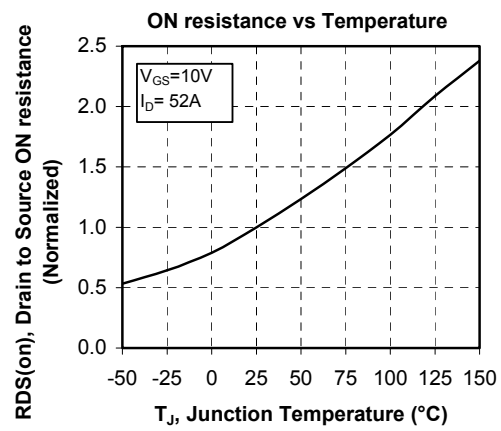
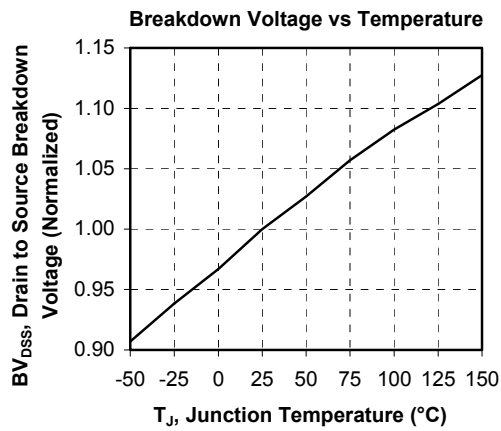
Side View Dimensions:

- Overall Width: 21.2 ± 1
- Overall Height: 40.40 ± 0.50
- Distance from Bottom Edge to Center of First Hole: 3 ± 0.20
- Distance from Bottom Edge to Center of Last Hole: 5 ± 0.50

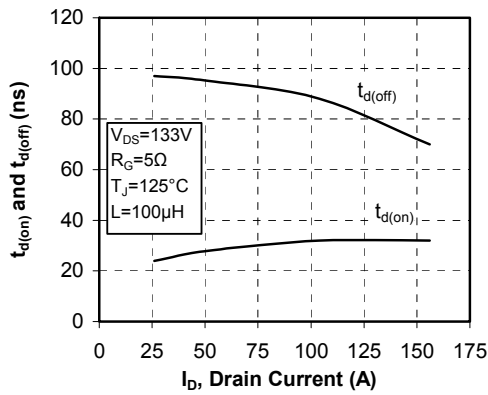
See application note APT0501 - Mounting Instructions for SP4 Power Modules on www.microsemi.com

Typical Performance Curve

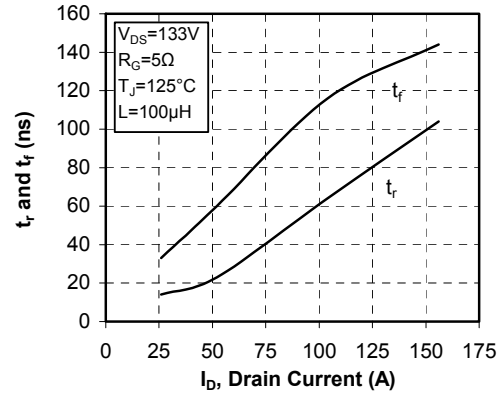




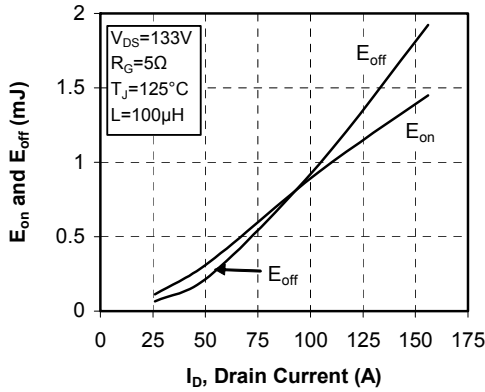
Delay Times vs Current



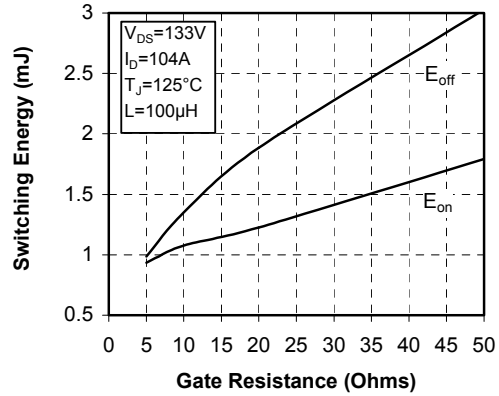
Rise and Fall times vs Current



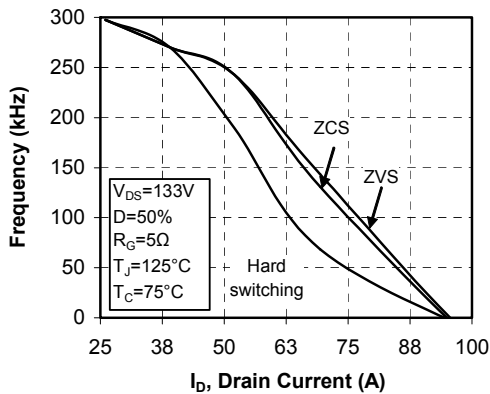
Switching Energy vs Current



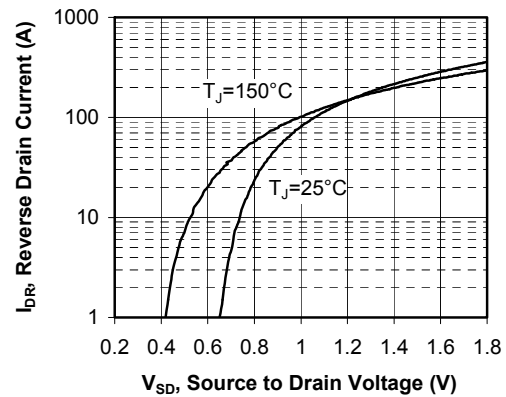
Switching Energy vs Gate Resistance



Operating Frequency vs Drain Current



Source to Drain Diode Forward Voltage



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